

PFC qualified new Dupont Material

RESEARCH TRIANGLE PARK, N.C., April 5, 2010 — DuPont Circuit & Packaging Materials (CPM) introduced its newest high-performance laminate for printed circuit boards. DuPont™ Pyralux® TK flexible circuit material is a copper clad laminate and bonding film system specifically formulated with DuPont™ Teflon® fluoropolymer film and Kapton® polyimide film for high speed digital and high frequency flexible circuit applications. DuPont™ Pyralux® TK delivers the lowest dielectric constant (DK) of any thin laminate and bondply material on the market today.

“Our ability to combine DuPont™ Teflon® and Kapton® technologies in Pyralux® TK has resulted in a product that is uniquely suited to high speed flexible circuit designs,” said Thomas D. Lantzer -- market segment leader, High Reliability & Telecom, DuPont Circuit & Packaging Materials.. “There is no glass in the construction of Pyralux® TK, so it’s ideal for flexible applications. Its combination of low dielectric constant, low loss tangent, low moisture tolerance and tight thickness tolerance are unparalleled in the industry today. DuPont continues to put science to work to expand its offerings, and we’re very pleased to add this to our Pyralux® portfolio to meet our customers’ needs for advanced high performance and high speed designs.”

With a dielectric constant (DK) of 2.3 to 2.7, and low loss dissipation factor (DF) of 0.002 or 0.003 depending on the film construction, Pyralux® TK is designed for high speed flex applications, including microstrip and stripline controlled impedance constructions. The clad dielectric is a proprietary layered composite of Teflon® and Kapton® films. A variety of copper foil weights are available; the standard foils are 18 and 35 micron rolled annealed (RA) copper. Pyralux® TK bonding film is also a layered dielectric, made with Teflon® and Kapton® films. The bonding film contains a Teflon® film with a lower lamination temperature than the clad. The Teflon® in the bonding film is also available separately as a sheet adhesive. Thin (2 to 4 mil) DuPont™ Pyralux® TK is available in laminate thicknesses of 50, 75 and 100 microns. Bondply thicknesses are available in 75 or 100 microns. DuPont also plans to offer a Pyralux® TK sheet adhesive in 12, 25, and 50 microns.